

# STS8C5H30L

Datasheet - production data

### N-channel 30 V, 0.018 Ω typ., 8 A, P-channel 30 V, 0.045 Ω typ., 5 A Power MOSFET in a SO-8 package

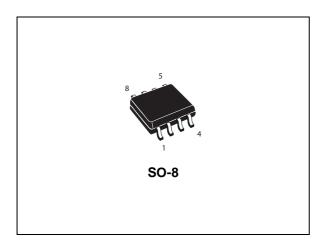
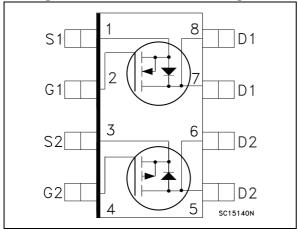


Figure 1. Internal schematic diagram



### Features

Order code	Channel	$V_{\text{DS}}$	R <sub>DS(on)</sub> max	I <sub>D</sub>
STS8C5H30L	Ν	30 V	0.022 Ω	8 A
5158C5H30L	Р	30 V	0.055 Ω	5 A

- Conduction losses reduced
- Switching losses reduced
- Low threshold drive
- Standard outline for easy automated surface mount assembly

### **Applications**

• Switching applications

### Description

This device is a complementary N-channel and Pchannel Power MOSFET developed using STripFET™ II (P-channel) and STripFET™ V (Nchannel) technologies. The resulting transistors show extremely high packing density for low onresistance and rugged avalanche characteristics.

### Table 1. Device summary

(	Order code	Marking	Packages	Packaging
S	STS8C5H30L	8C5H30L	SO-8	Tape and reel

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This is information on a product in full production.

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## 1 Electrical ratings

Symbol	Parameter	Val	Unit		
Symbol	Falameter	N-channel	P-channel	Onit	
V <sub>DS</sub>	Drain-source voltage	30	)	V	
V <sub>GS</sub>	Gate- source voltage ±		±16	V	
۱ <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25°C single operating	8	5.4	А	
۱ <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100°C single operating	6.4	4.3	A	
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	32 21.6		А	
P	Total dissipation at $T_{C}$ = 25°C dual operating	1.6		W	
$P_{TOT}$ Total dissipation at $T_C = 25^{\circ}C$ single operating		2		W	
T <sub>stg</sub>	Storage temperature	-55 to 150		°C	
Тj	Operating junction temperature	15	0	°C	

1. Pulse width limited by safe operating area

Table 3. Thermal data

Symbol Parameter		Value	Unit
R <sub>thj-a</sub> <sup>(1)</sup>	Thermal resistance junction-ambient single operating	62.5	°C/W
R <sub>thj-a</sub> <sup>(1)</sup>	Thermal resistance junction-ambient dual operating	78	°C/W

1. When mounted on 1 inch² FR-4 board, 2 oz. Cu., t  $\leq$  10 sec

Note: For the p-channel MOSFET actual polarity of voltages and current has to be reversed



## 2 Electrical characteristics

(T<sub>CASE</sub> = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Channel	Min.	Тур.	Max.	Unit
.,	Drain-source		N	30			V
V <sub>(BR)DSS</sub>	breakdown voltage	V <sub>GS</sub> = 0, I <sub>D</sub> = 250 μA	Р	30			V
	Zana mata walta na	$V_{GS} = 0, V_{DS} = 30 V$	N			1	μA
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>GS</sub> = 0, V <sub>DS</sub> =30 V, T <sub>C</sub> =125 °C	Р			10	μA
1	I <sub>GSS</sub> Gate-body leakage current	$V_{DS} = 0, V_{GS} = \pm 16 V$	Ν			±100	nA
GSS		$V_{DS} = 0, V_{GS} = \pm 16 V$	Р			±100	nA
V	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	Ν	1	1.6	2.5	V
V <sub>GS(th)</sub>	Gale intestion voltage		1	1.6	2.5	V	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A	N		0.018	0.022	Ω
BDO(an)	Static drain-source	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 2.5 \text{ A}$	Р		0.045	0.055	Ω
	on-resistance	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 4 \text{ A}$	N		0.020	0.025	Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 2.5 \text{ A}$	Р		0.070	0.075	Ω

Table 4. On/off states



Symbol	Parameter	Test conditions	Channel	Min.	Тур.	Max.	Unit
g <sub>fs</sub> <sup>(1)</sup> Forward		V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4 A	N	-	8.5		S
9fs V	transconductance	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 2.5 A	Р	-	10		S
C			N	-	857		pF
C <sub>iss</sub>	Input capacitance		Р	-	1350		pF
<u> </u>		V <sub>GS</sub> = 0, V <sub>DS</sub> = 25 V, f = 1 MHz	N	-	147		pF
C <sub>oss</sub>	Output capacitance		Р	-	490		pF
C	Reverse transfer		N	-	20		pF
C <sub>rss</sub>	capacitance		Р	-	130		pF
0	Total acta obarga	N-channel	N	-	7	10	nC
Qg	Total gate charge	V <sub>DD</sub> =24 V I <sub>D</sub> =8 A	Р	-	12.5	16	nC
0		V <sub>GS</sub> =5 V P-channel V <sub>DD</sub> = 24 V I <sub>D</sub> = 4 A	N	-	2.5		nC
Q <sub>gs</sub>	Gate-source charge		Р	-	5		nC
0	Cata drain abarra	V <sub>GS</sub> = 5 V	N	-	2.3		nC
Q <sub>gd</sub>	Gate-drain charge	(see Figure 27)	Р	-	3		nC

Table 5. Dynamic

1. Pulsed: Pulse duration =  $300 \mu$ s, duty cycle 1.5.

For the p-channel MOSFET actual polarity of voltages and current has to be reversed

Symbol	Parameter	Test conditions	Channel	Min.	Тур.	Max.	Unit
<b>t</b>	Turre en deleu tirre e		Ν	-	12	-	ns
t <sub>d(on)</sub>	Turn-on delay time	N-channel	Р	-	25	-	ns
+	Rise time	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 4 A	Ν	-	14.5	-	ns
t <sub>r</sub>		R <sub>G</sub> =4.7 Ω, V <sub>GS</sub> = 4.5 V P-channel	Р	-	35	-	ns
t	Turn-off delay time	$V_{DD} = 15 \text{ V}, \text{ I}_{D} = 2 \text{ A}$	Ν	-	23	-	ns
t <sub>d(off)</sub>	off) Turn-on delay time	R <sub>G</sub> =4.7 Ω, V <sub>GS</sub> = 4.5 V	Р	-	125	-	ns
+.	Fall time	Figure 26	Ν	-	8	-	ns
t <sub>f</sub>			Р	-	35	-	ns

Table 6. Switching times



Symbol	Parameter	Test conditions	Channel	Min.	Тур.	Max.	Unit
	Source-drain current		Ν	-		8	А
I <sub>SD</sub>	Source-drain current		Р	-		5	А
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current		Ν	I		32	А
'SDM `	(pulsed)		Р	-		20	А
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	$I_{SD} = 8 A, V_{GS} = 0$	Ν	-		1.5	V
V SD V	V <sub>SD</sub> <sup>(2)</sup> Forward on voltage	I <sub>SD</sub> = 5 A, V <sub>GS</sub> = 0	Р	-		1.2	V
+	Reverse recovery	N-channel	Ν	-	15		ns
t <sub>rr</sub>	time	I <sub>SD</sub> = 8 A, di/dt = 100 A/μs	Р	-	45		ns
0	Reverse recovery	V <sub>DD</sub> =15 V,T <sub>j</sub> =150 °C P-channel	Ν	-	5.7		nC
Q <sub>rr</sub>	charge	I <sub>SD</sub> = 5 A, di/dt = 100 A/μs	Р	-	36		nC
	Reverse recovery	V <sub>DD</sub> =15 V, T <sub>j</sub> =150 °C	N	-	0.76		А
'RRM	I <sub>RRM</sub> current	Figure 28	Р	-	1.6		А

Table 7. Source drain diode

1. Pulse width limited by safe operating area.

2. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5%

Note: For the p-channel MOSFET actual polarity of voltages and current has to be reversed



### 2.1 Electrical characteristics (curves)

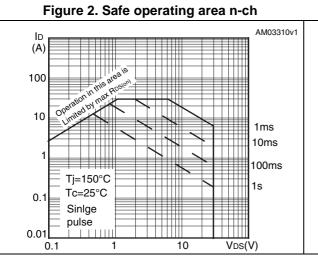


Figure 4. Output characteristics n-ch

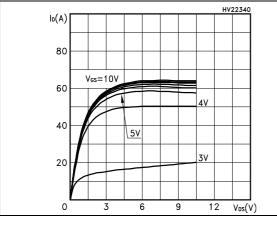


Figure 6. Transconductance n-ch

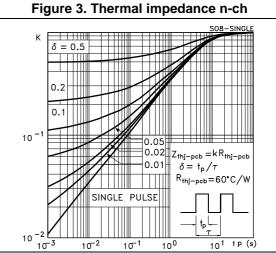
TJ=-55°C

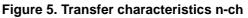
2

1

175°C

3





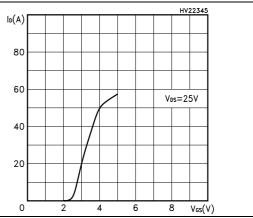
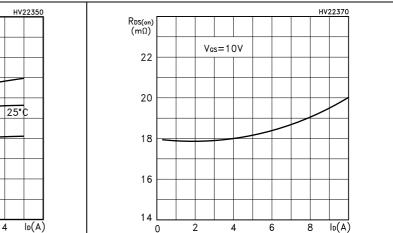


Figure 7. Static drain-source on resistance n-ch





 $g_{fs}(S)$ 

12

9

6

3

0

Figure 8. Gate charge vs. gate-source voltage n-ch

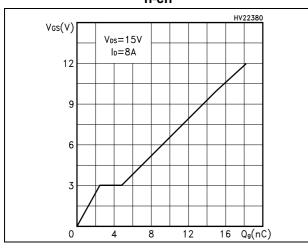


Figure 10. Normalized gate threshold voltage vs. temperature n-ch

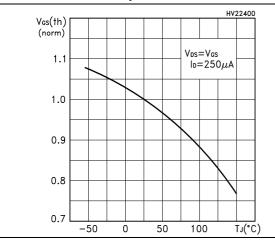


Figure 12. Source-drain diode forward characteristics n-ch

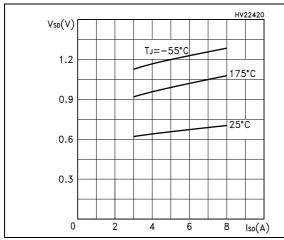


Figure 9. Capacitance variations n-ch

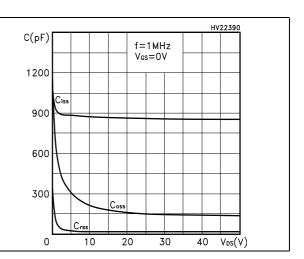


Figure 11. Normalized on resistance vs. temperature n-ch

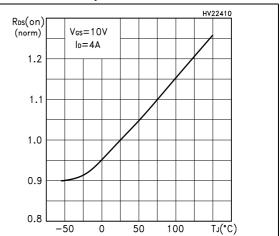
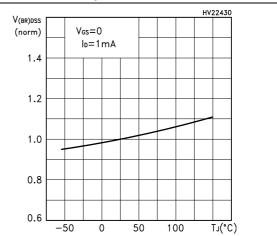


Figure 13. Normalized breakdown voltage vs. temperature n-ch





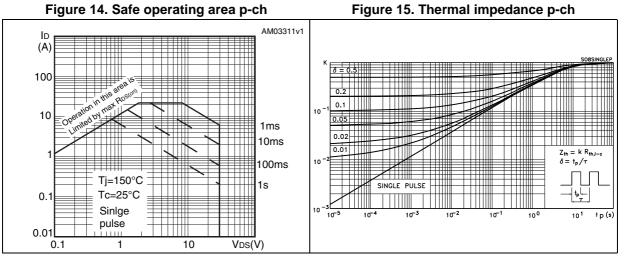
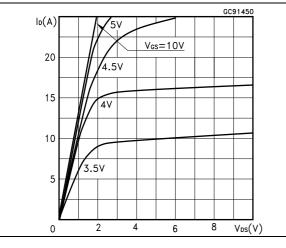
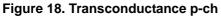


Figure 16. Output characteristics p-ch





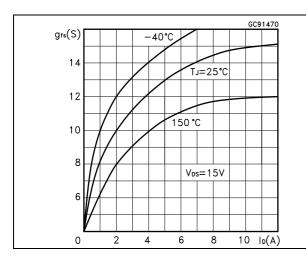


Figure 17. Transfer characteristics p-ch

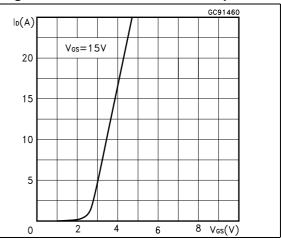


Figure 19. Static drain-source on resistance p-ch

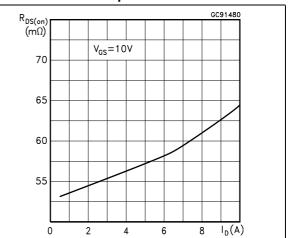




Figure 20. Gate charge vs. gate-source voltage p-ch

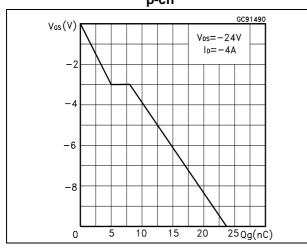


Figure 22. Normalized gate threshold voltage vs. temperature p-ch

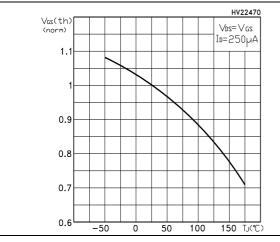


Figure 24. Source-drain diode forward characteristics p-ch

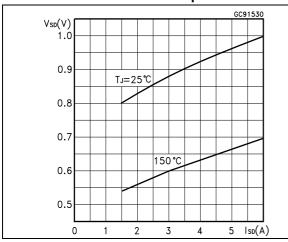


Figure 21. Capacitance variations p-ch

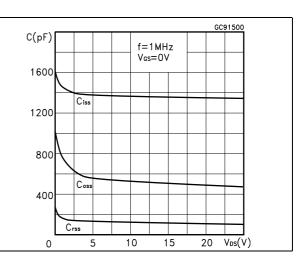


Figure 23. Normalized on resistance vs. temperature p-ch

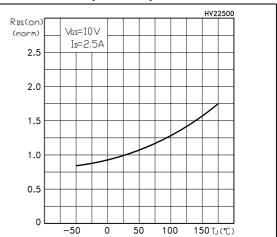
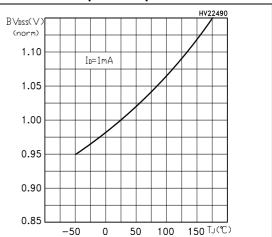


Figure 25. Normalized breakdown voltage vs. temperature p-ch



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#### **Test circuits** 3

Figure 26. Switching times test circuit for resistive load

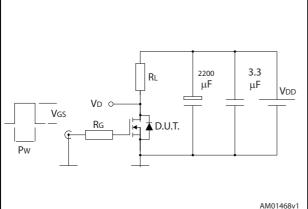


Figure 28. Test circuit for inductive load switching and diode recovery times

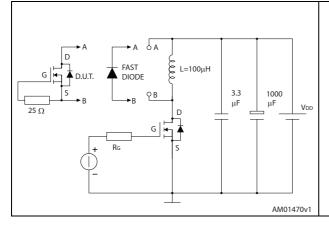
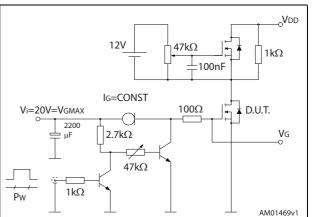


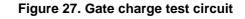
Figure 30. Unclamped inductive waveform

VD

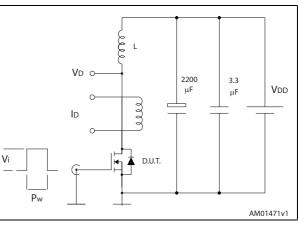
IDM

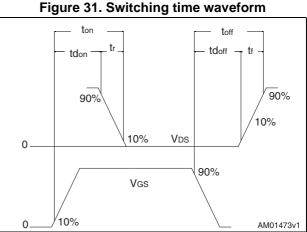
lр











V(BR)DSS



Vdd

Vdd

AM01472v1

### 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.

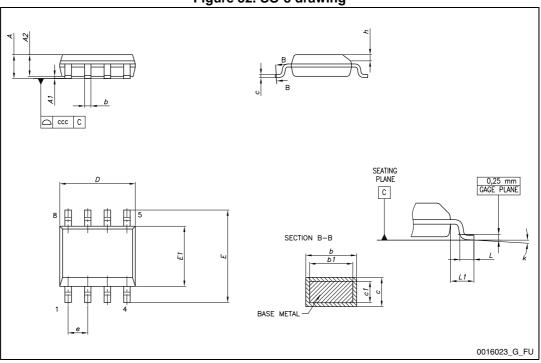


Figure 32. SO-8 drawing



		J-o mechanical uala	
Dim.		mm	
Dini.	Min.	Тур.	Max.
А			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
С	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
е		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

Table 8. SO-8 mechanical data



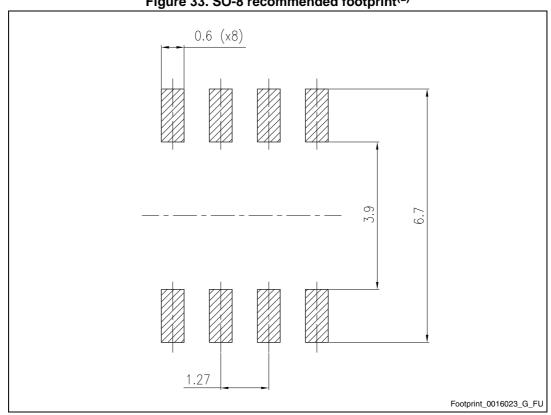


Figure 33. SO-8 recommended footprint<sup>(a)</sup>

a. All dimensions are in millimeters.

### 5 Packaging mechanical data

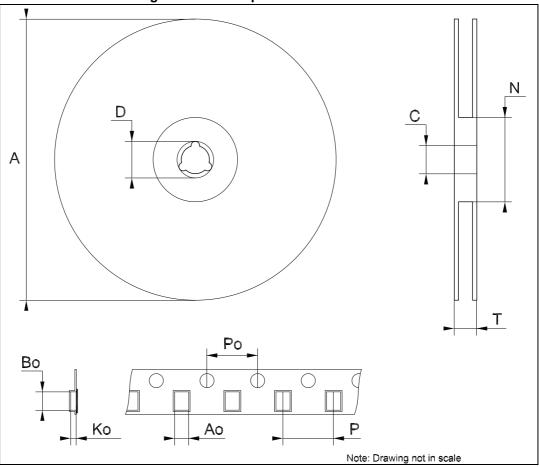


Figure 34. SO-8 tape and reel dimensions



Dim.		mm	
Dim.	Min.	Тур.	Max.
А		-	330
С	12.8	-	13.2
D	20.2	-	
N	60	-	
Т		-	22.4
Ao	8.1	-	8.5
Во	5.5	-	5.9
Ko	2.1	-	2.3
Po	3.9	-	4.1
Р	7.9	-	8.1

Table 9. SO-8 tape and reel mechanical data



## 6 Revision history

Date	Revision	Changes
17-Sep-2004	1	First revision.
31-Oct-2006	2	The document has been reformatted.
30-Jan-2007	3	typo mistake on <i>Table 2</i> .
23-Jul-2007	4	Figure 14 has been updated.
23-Feb-2009	5	Figure 2, Figure 3, Figure 14 and Figure 15 have been changed.
10-Jun-2010	6	Updated V <sub>GS(th)</sub> in <i>Table 4: On/off states</i> .
13-Jun-2014	7	<ul> <li>Modified: title</li> <li>Modified: Description</li> <li>Modified: marking in Table 1</li> <li>Updated: Section 4: Package mechanical data</li> <li>Minor text changes</li> </ul>

#### Table 10. Revision history



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